

# SOT908-1

plastic thermal enhanced very thin small outline package; no leads; 8 terminals

10 June 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	HVSON8
<b>Package type industry code</b>	HVSON8
<b>Package style descriptive code</b>	HVSON (thermal enhanced very thin small outline; no leads)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-229
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	5-10-2005

Table 1. Package summary

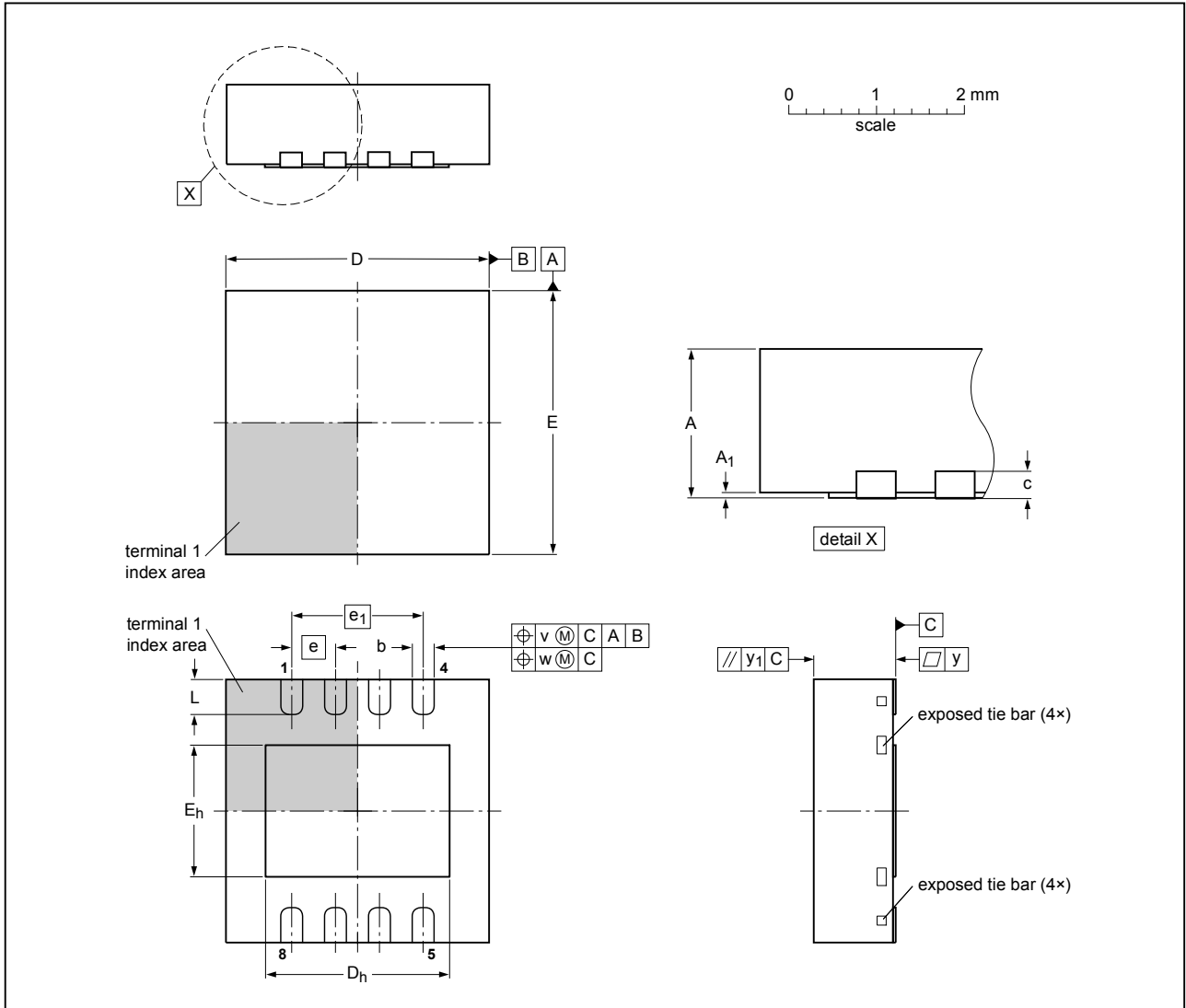
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.9	-	3	3.1	mm
E	package width	2.9	-	3	3.1	mm
A	seated height	-	-	0.85	1	mm
A <sub>2</sub>	package height	-	-	-	-	
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	8	-	



## 2. Package outline

HVSON8: plastic thermal enhanced very thin small outline package; no leads; 8 terminals; body 3 x 3 x 0.85 mm

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**DIMENSIONS** (mm are the original dimensions)

UNIT	A <sup>(1)</sup> max.	A <sub>1</sub>	b	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	e <sub>1</sub>	L	v	w	y	y <sub>1</sub>
mm	1	0.05 0.00	0.3 0.2	0.2	3.1 2.9	2.25 1.95	3.1 2.9	1.65 1.35	0.5	1.5	0.5 0.3	0.1	0.05	0.05	0.1

**Note**

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

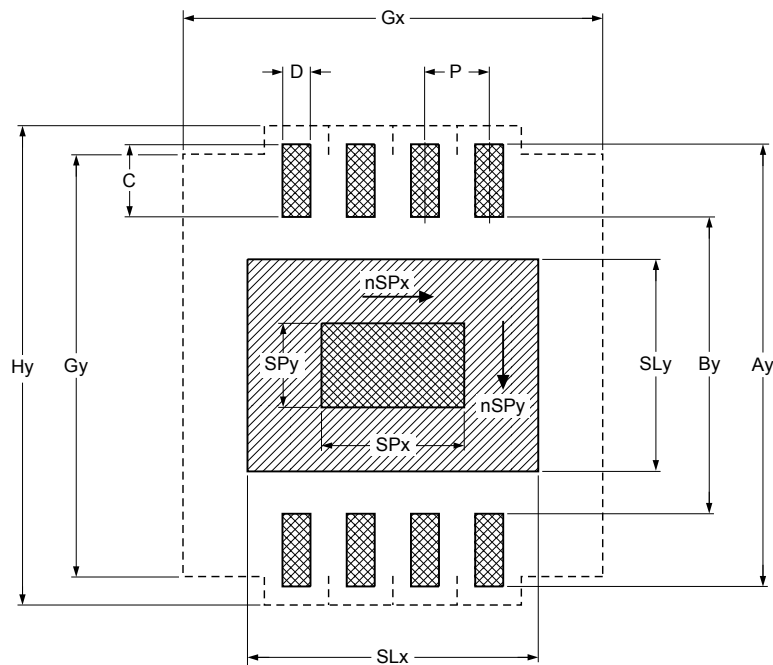
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT908-1		MO-229				05-09-26 05-10-05




Fig. 1. Package outline HVSON8 (SOT908-1)

### 3. Soldering

Footprint information for reflow soldering of HVSON8 package

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-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area

DIMENSIONS in mm

P	Ay	By	C	D	SLx	SLy	SPx	SPy	Gx	Gy	Hy
0.5	3.45	2.25	0.6	0.25	2.25	1.65	1.1	0.65	3.25	3.25	3.7

nSPx	nSPy
1	1

Issue date 12-02-09  
12-02-28

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Fig. 2. Reflow soldering footprint for HVSON8 (SOT908-1)

## 4. Legal information

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Date of release: 10 June 2016

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